

Microbonds



MICROBONDS AND PROMEX INDUSTRIES INC. ANNOUNCE BROAD MARKET X-WIRE™ ALLIANCE

(Toronto, Canada & Santa Clara, California) (July 16, 2007)

Microbonds Inc. a privately held Canadian corporation and Promex Industries, Inc. a privately held IC assembly and packaging foundry are pleased to announce a co-development alliance to qualify and offer Microbonds X-Wire™ to the broad IC assembly and packaging market.

Promex Industries (www.promex-ind.com) is a leader in new product introduction, materials-centric custom package development & assembly, and mainstream IC assembly services.

Microbonds insulated X-Wire™ Technology (www.microbonds.com) allows bonding wires to touch without electrical shorting, permitting fuller utilization of the x, y and z dimensions in electronic package design. The technology increases bonding flexibility by allowing a., wires to cross, b. denser bonding designs (because wire spacing is no longer critical) c., the potential for some wire sweep in molding and, d., control of bonding wire impedance (with ground wires parallel to signal wires). These capabilities help reduce package size and manufacturing defects.

Each generation of packaging technology is continuously driven by lower cost, higher complexity, higher density and greater functionality. In addition, there are enormous market pressures for shorter development cycles.

The alliance will allow Promex to offer X-Wire™ to its expanding customer base seeking highest quality IC assembly and custom package development and assembly services.

Richard Otte, CEO of Promex stated, "We are excited by the Microbonds alliance and by the promise of X-Wire™ Technology for new package development and production assembly. Package designers will gain an impressive new level of layout flexibility and enhanced performance utilizing smaller package sizes. We feel strongly this alliance allows customers to take advantage of the distinctive competencies of two leading-edge companies."

John Scott, CEO of Microbonds noted, “We are very pleased to be allied with Promex Industries, a proven leader in IC assembly and packaging services. This alliance will provide us and our licensees to serve the advanced packaging and design needs of the fabless segment of the marketplace. This collaborative effort continues our approach of bringing X-Wire™ to the market with proven industry partners in order to minimize the time, cost and risk of adoption of this new technology and provides companies interested in X-Wire™ an avenue for rapid qualification and implementation”.

About Microbonds

Microbonds, Inc. is the leading developer and licensor of insulated wire bonding technologies for use in the package design and assembly of microelectronic devices. Their web site address is www.microbonds.com

About Promex Industries, Inc.

Promex (www.promex-ind.com) is a unique materials-centric packaging foundry and IC assembly service provider. Molded plastic, ceramic and custom packaging solutions including SiP's, MEMS, MOEMS, MCM's and LGA's are provided utilizing broad technical capabilities and RoHS expertise. Scaleable capacity allows customer prototyping and “fast tracked” new product introductions including pre-Asia volume manufacturing .

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